

a specialized apparatus for performing wire-bonding operations in an integrated circuit. Further, as is commonly known in the art, due to the extremely small tolerances involved in wire-bonding operations of an integrated circuit, it is not possible to perform such a wire-bonding process "by hand without the need for a specialized apparatus." Accordingly, Applicants assert that, in view of the foregoing remarks and in the interest of conservation of resources for the Patent Office as well as the Applicants, claims 1-23 should be examined together. Withdrawal of the restriction requirement in the present application is therefore respectfully solicited.

Notwithstanding the above traversal, Applicants hereby provisionally elect the claims of Group I, namely, claims 1-21, for prosecution on the merits.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Robert W. Griffith", written in a cursive style.

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